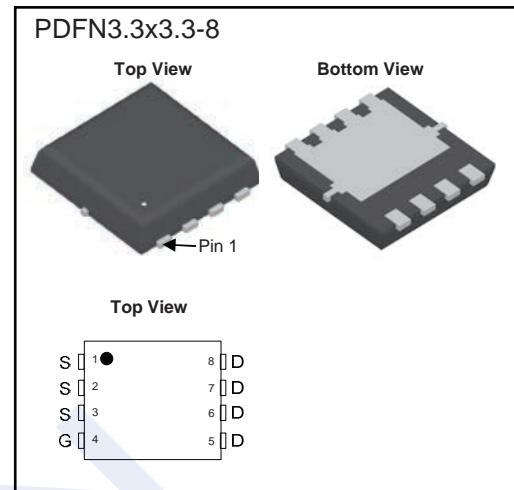
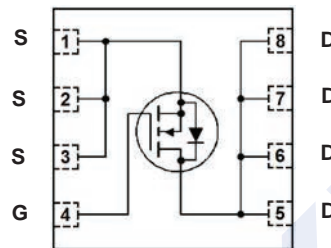


N-Channel MOSFET

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■ Features

- $V_{DS} (V) = 150V$
- $I_D = 17 A$
- $R_{DS(ON)} = 54m\Omega (V_{GS} = 10V)$
- $R_{DS(ON)} = 66m\Omega (V_{GS} = 6V)$

■ Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V_{DS}	150	V	
Gate-Source Voltage	V_{GS}	± 20		
Continuous Drain Current	I_D	$T_C = 25^\circ C$	17	A
		$T_C = 100^\circ C$	11	
Pulsed Drain Current (Note 3)	I_{DM}	30		
Continuous Drain Current	I_{DSM}	$T_A = 25^\circ C$	5.5	
		$T_A = 70^\circ C$	4.5	
Single Pulse Avalanche Current (Note 3)	I_{AS}	15		
Single Pulse Avalanche Energy (Note 3)	$L = 0.3mH$	EAS	34	mJ
Power Dissipation (Note 2)	P_D	$T_C = 25^\circ C$	38	W
		$T_C = 100^\circ C$	15.5	
Power Dissipation (Note 1)	P_{DSM}	$T_A = 25^\circ C$	4.1	
		$T_A = 70^\circ C$	2.6	
Thermal Resistance.Junction- to-Ambient (Note 1)	$t \leq 10s$	$R_{\theta JA}$	30	$^\circ C/W$
Thermal Resistance.Junction- to-Case	Steady state	$R_{\theta JC}$	3.2	
Junction Temperature	T_J	150	$^\circ C$	
Storage Temperature Range	T_{stg}	-55 to 150		

Notes:

1. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ ($t \leq 10s$) and the maximum allowed junction temperature of $150^\circ C$. The value in any given application depends on the user's specific board design.
2. The power dissipation P_D is based on $T_{J(MAX)} = 150^\circ C$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
3. Single pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ C$.

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■ Electrical Characteristics (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
STATIC PARAMETERS						
Drain-Source Breakdown Voltage	BV _{DSS}	I _D =250μA, V _{GS} =0V	150			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =150V, V _{GS} =0V			1	μA
		V _{DS} =150V, V _{GS} =0V, T _J =55°C			5	
Gate-Body Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2		4	V
Static Drain-Source On-Resistance (Note 4)	R _{DS(on)}	V _{GS} =10V, I _D =5A		54	80	mΩ
		V _{GS} =10V, I _D =5A, T _J =125°C		107		
		V _{GS} =6V, I _D =2A		66	95	
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =5A		17		S
Maximum Body-Diode Continuous Current	I _S	T _C =25°C			17	A
Diode Forward Voltage	V _{SD}	I _S =1A, V _{GS} =0V			1.0	V
DYNAMIC PARAMETERS (Note 5)						
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =75V, f=1MHz		675		pF
Output Capacitance	C _{oss}			78		
Reverse Transfer Capacitance	C _{rss}			4		
Gate resistance	R _g	f=1MHz	1.4		4.4	Ω
SWITCHING PARAMETERS (Note 5)						
Turn-On Delay Time	t _{d(on)}	V _{GS} =10V, V _{DS} =75V, R _L =15Ω, R _{GEN} =3Ω		6		ns
Turn-On Rise Time	t _r			3		
Turn-Off Delay Time	t _{d(off)}			20		
Turn-Off Fall Time	t _f			5		
Body Diode Reverse Recovery Time	t _{rr}	I _F = 5A, di/dt = 500A/μs		37		ns
Body Diode Reverse Recovery Charge	Q _{rr}			210		nC

Notes:

- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%
- Guaranteed by design, not subject to production testing.

■ Marking

Marking	K5097 KC****
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Typical Electrical And Thermal Characteristics

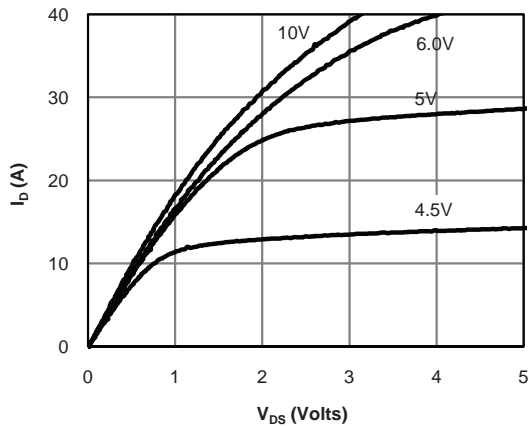


Figure 1: On-Region Characteristics

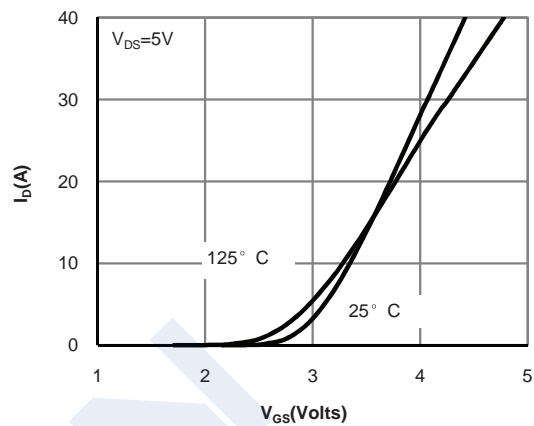


Figure 2: Transfer Characteristics

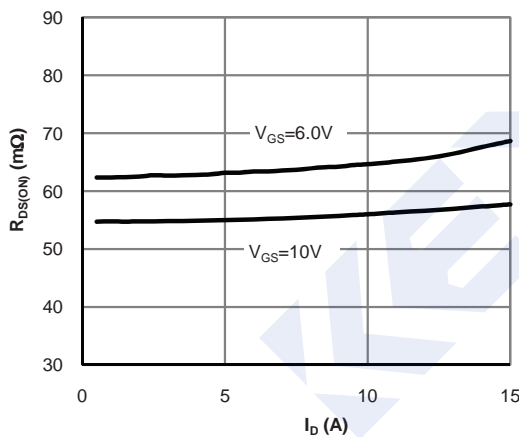


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

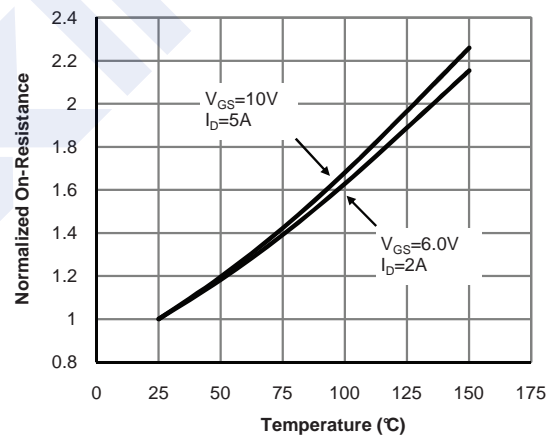


Figure 4: On-Resistance vs. Junction Temperature

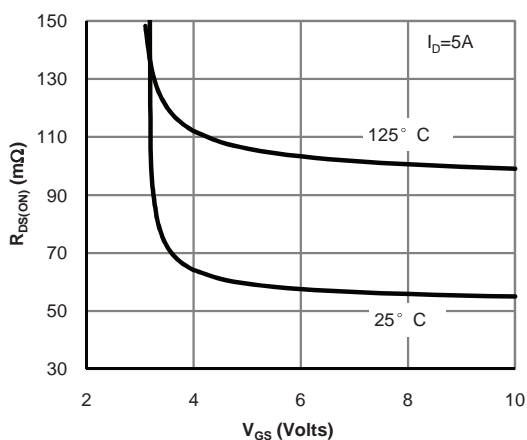


Figure 5: On-Resistance vs. Gate-Source Voltage

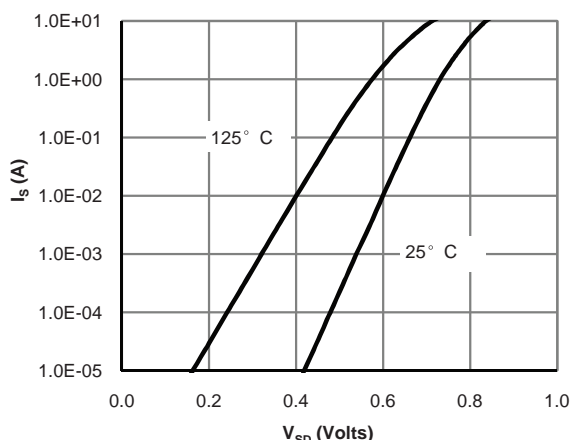


Figure 6: Body-Diode Characteristics

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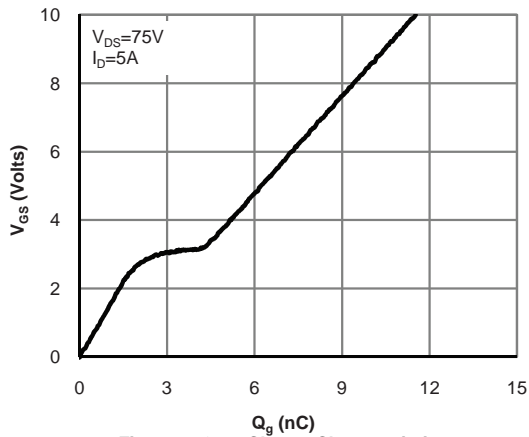


Figure 7: Gate-Charge Characteristics

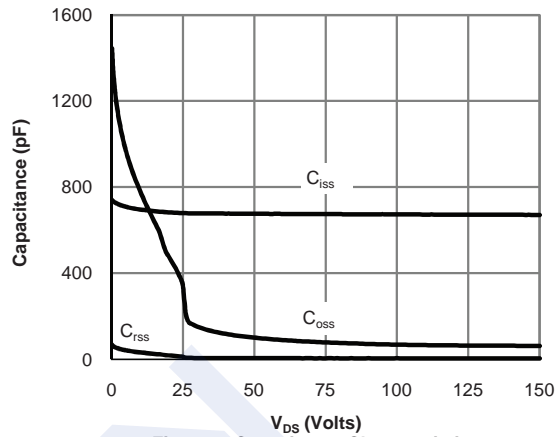


Figure 8: Capacitance Characteristics

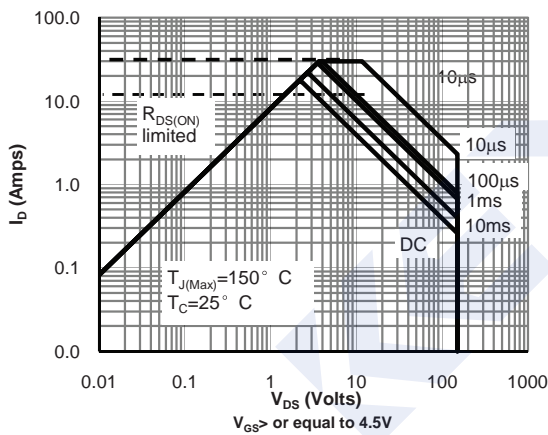


Figure 9: Maximum Forward Biased Safe Operating Area

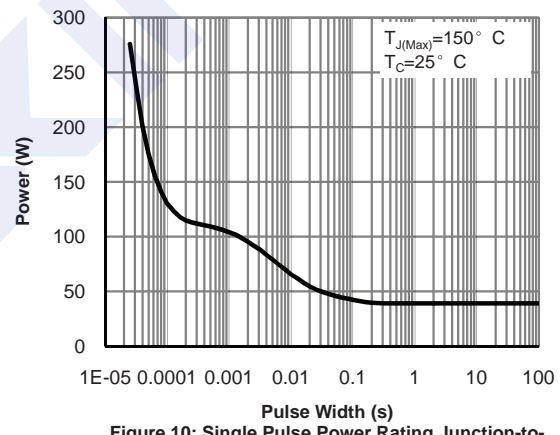


Figure 10: Single Pulse Power Rating Junction-to-Case

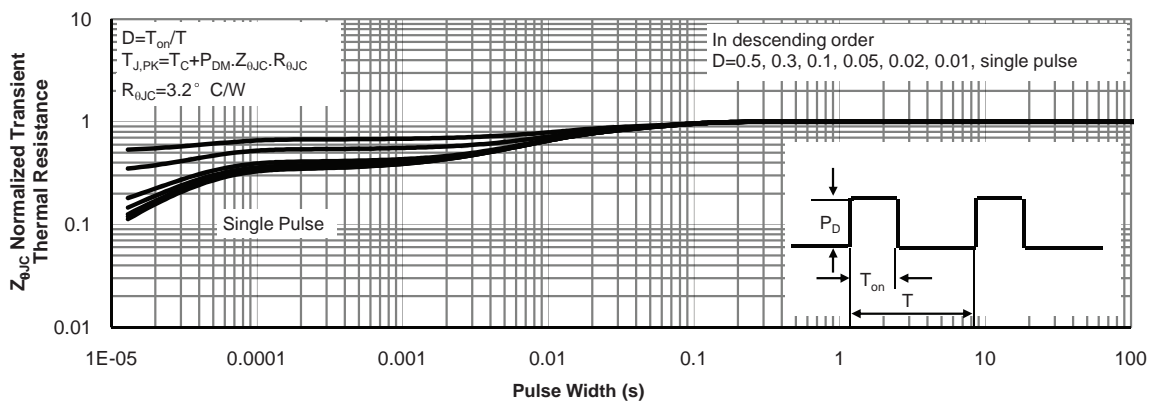
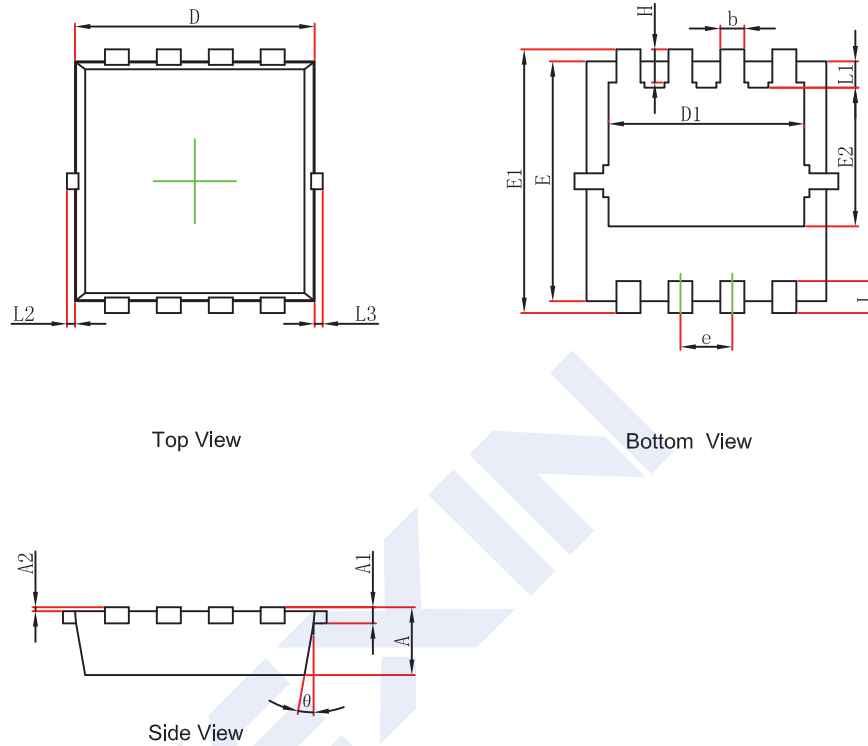


Figure 11: Normalized Maximum Transient Thermal Impedance

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■ PDFN3.3x3.3-8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	3.050	3.250	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°